

PATENT APPLICATION

IN THE U.S. PATENT AND TRADEMARK OFFICE

August 5, 2008

Applicants: Atsushi YABE et al
Title: ELECTROLESS COPPER PLATING SOLUTION AND
ELECTROLESS COPPER PLATING METHOD

Serial No.: 10/576 230 Group: 1792
Confirmation No.: 7180
Filed: April 14, 2006 Examiner: Bareford
International Application No.: PCT/JP2004/014049
International Filing Date: September 17, 2004
Atty. Docket No.: 4700.P0328US
Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Herewith is an amendment in the above-identified application.

☐ Applicant claims small entity status. See 37 CFR 1.27.

☐ The additional filing fee has been calculated as shown below:

For	No. Filed	No. Extra	(X) LG Entity	RATE	() SM Entity	Fee
Total Claims	(2 - 20 = 0)		x	\$ 50.00	x	\$ 25.00
Indep. Claims	(1 - 3 = 0)		x	\$210.00	x	\$105.00
<input type="checkbox"/> Multiple Dep. Claim			+	\$370.00	+	\$185.00
* * * TOTAL FILING FEE * * *						\$ 0.00

☐ Pursuant to 37 CFR 1.136(a), please extend the shortened period for response by month(s). The extension fee is: \$.

☐ A Check for \$ is enclosed to cover fees.

☒ Please credit any overpayment, or charge any additional filing fee required under 37 CFR 1.16 or 1.17 by this communication, to Deposit Account No. 06-1382. A duplicate copy of this sheet is enclosed.

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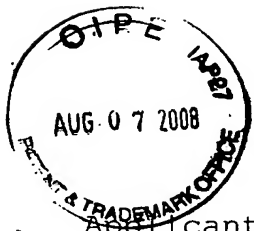
Terryence F. Chapman Reg. No. 32 549

CERTIFICATE OF MAILING

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Terryence F. Chapman



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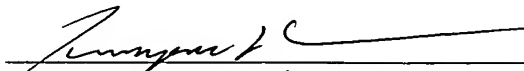
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